

# COBRA – TU/e packaging requirements

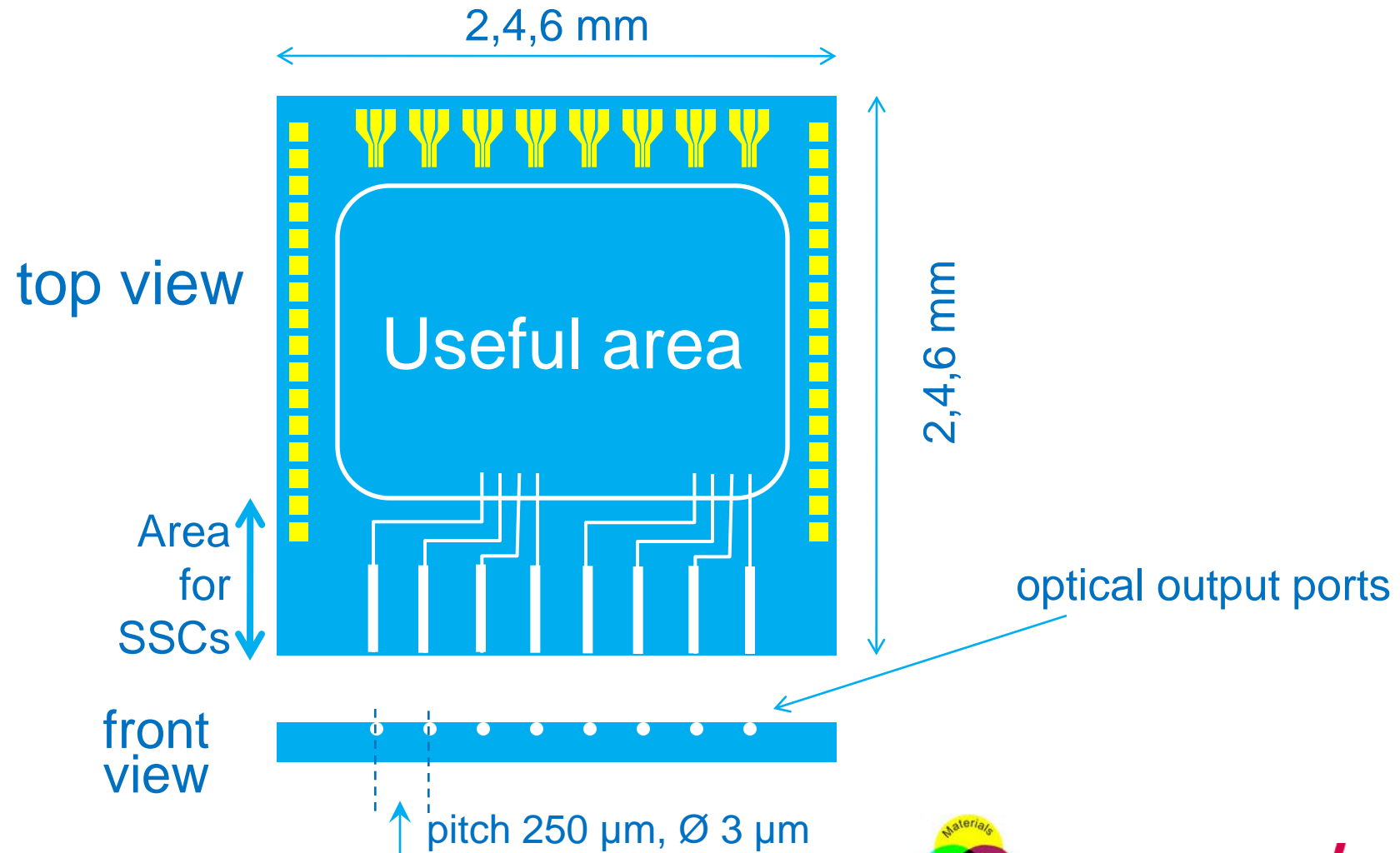
Meint Smit



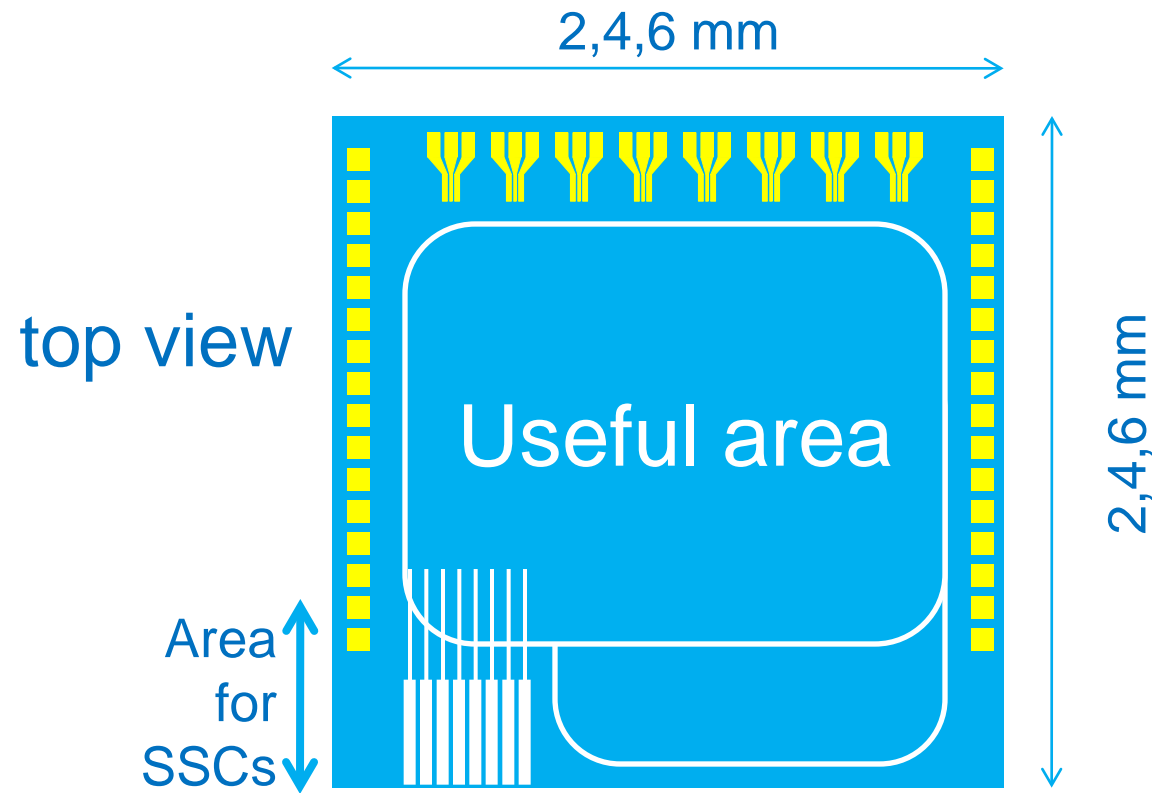
**TU/e** Technische Universiteit  
Eindhoven  
University of Technology

Where innovation starts

# PARADIGM PIC with 250 $\mu\text{m}$ pitch SSCs



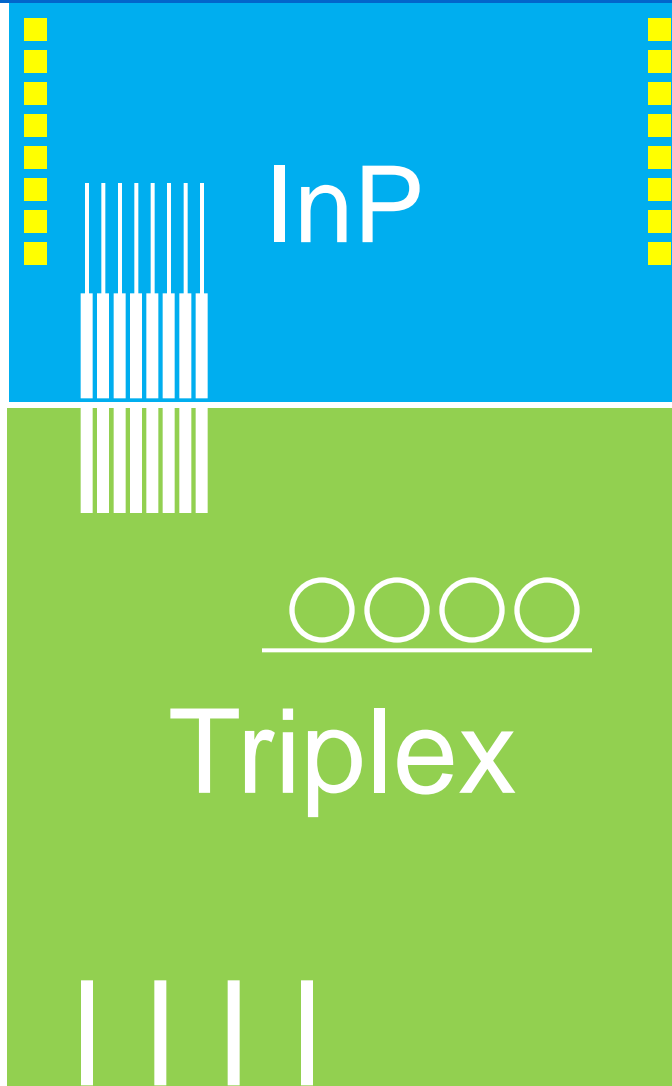
# PARADIGM PIC with 25 $\mu\text{m}$ pitch SSCs



or



# Triplex interposer with 25/250 $\mu\text{m}$ pitch



## Advantages:

- High alignment accuracy required in a small area only
- Hybrid platform with optical bus
- For small pitch an interposer is required anyhow, hybrid platform comes for free